

# F1 Smart Module

Label information document

July 30, 2024

## F1 Smart Module label types

***For F1 Smart Module labeling, there are two main types:***

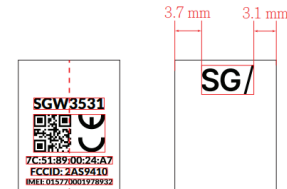
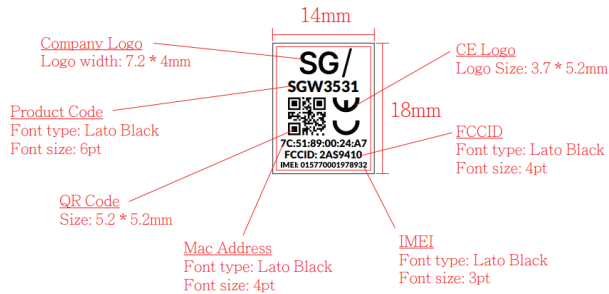
1. Label on modules
2. Label on packing

# Label on module

# F1 Smart Module label on module

*F1 Smart module **upper** shield can label details (Printing method: Laser etch)*

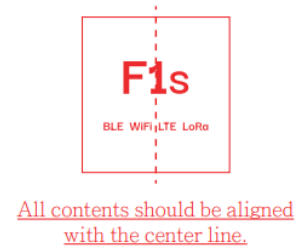
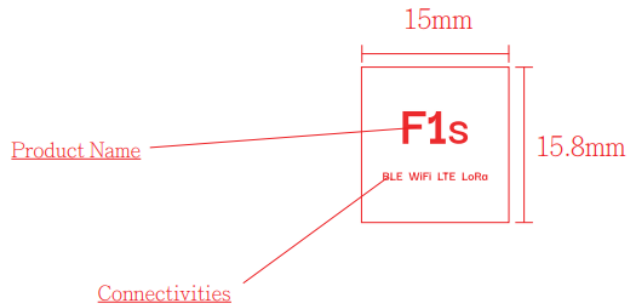
## Guidelines:



# F1 Smart Module label on module

*F1 Smart module **lower** shield can label details (Printing method: Label print)*

## Guidelines:



# F1 Smart Module label on module

*Effect and sample photo of F1 Smart Module labels on module*



# Label on packing

# F1 Smart Module label on packing

## ***Locations that require labels:***

1. Product label on tape and reel
  - Label needed:
    - i. Label A*
  
2. Product label on Moisture-Barrier Bag (Anti-static Bag)
  - Label needed:
    - i. Label A*
    - ii. Precaution label*
  
3. Product label on Pizza Box
  - Label needed:
    - i. Label A*
    - ii. Label B*
  
4. Product label on Outer Box
  - Label needed:
    - i. Label C*



# F1 Smart Module Label size with dimension

Label A Size :

- 45mm x 90mm










# F1 Smart Module Label size with dimension




Label B Size : 50mm x 90mm

# F1 Smart Module Label size with dimension

Label C Size :  
100mm x 175mm

100 mm	
<b>SG</b> / Enabling Innovators	
Device: SGW2828-01A 	
P/O: SGW PO-20190005 DA 	
Lot No.: 19071901 	19071401 
Trace Code: 1930 	
QTY: 2000 	
PACKAGE COUNT: of	PACKAGE WEIGHT: KGS
Manufacturer: SG Wireless Limited Unit 4, 5/F, Sun Fung Industrial Building 8 Ma Kok Street, Tsuen Wan, New Territories, Hong Kong	
COUNTRY OF ORIGIN:CHINA	
	
175 mm	

# F1 Smart Module extra packing material



Caution  
Moisture-Sensitive  
MSL3

**CAUTION**  
**This Bag Contains**  
**MOSITURE SENSITIVE DEVICES**

**LEVEL**  
**3**

1.Shelf life in sealed bag: 12 Months at <40°C and < 90% relative humidity (RH)

2.After this bag is opened, devices that will be subjected to reflow solder or other high temperature process must be:

- a). Mounted within **168** hours at factory conditions of  $\leq 30^{\circ}\text{C} / 60\% \text{RH}$

or

- b). Stored at < 10%RH

3.Devices require bake, before mounting, if:

- a). Humidity indicator card is >10% when read at  $23^{\circ}\text{C} \pm 5^{\circ}\text{C}$
- b). 2a or 2b is not met

4. If baking in required, devices may be baked for 48 hours at  $125^{\circ}\text{C} \pm 5^{\circ}\text{C}$

Note: As plastic container cannot be subjected to high temperature, devices must be removed prior to high temperature ( $125^{\circ}\text{C}$ ) bake.  
If shorter bake times are desired, refer to IPC/JEDEC J-STD-033 for bake procedure  
Note: Level is defined by IPC/JEDEC J-STD-020

Figure 4. Precaution label on Anti-static bag

## F1 Smart Module packing extra material

The humidity-indicator card (See Figure 5) is placed inside the sealed moisture-barrier bag. This card verifies that the product has been stored and shipped in a low-humidity environment.

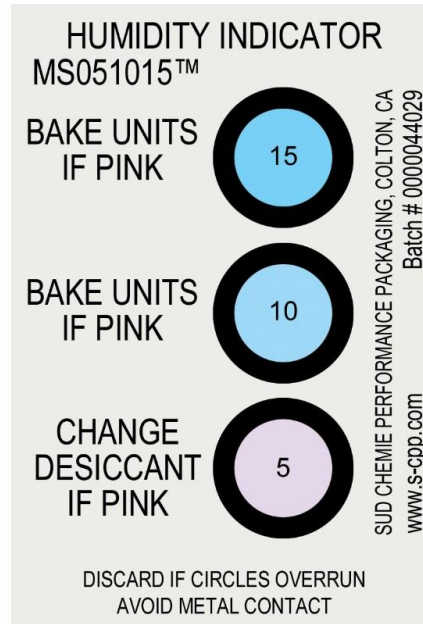


Figure 5. Humidity-Indicator Card

## F1 Smart Module Tape and Reel Packing way

“Label A”

a) Desiccant / Silica-gel

b) humidity indicator card has  
been stuck on the reel

c) Anti-static bag

d) Pizza box



*Pack into*



Figure 6. Dry-Packed Tape-and-Reel Configuration

## F1 Smart Module Pizza box and Outer box Packing way

Pizza boxes, Layer pads and Outer box Packing:

- Modules come on 330mm reels loaded with 250 modules. Each reel is placed in an antistatic bag with a desiccant pack and humidity card and placed in a 358 x 338 x 70 mm pizza box.
- First of all, a bottom layer pad is placed inside the outbox, then 5 pizza boxes are packed into the outer box, and finally a top layer pad is also placed on top of those 5 pizza boxes to complete the boxes packing
- So, ultimately the total module quantity is 1,250 pieces for each carton box with 5 separate pizza boxes inside

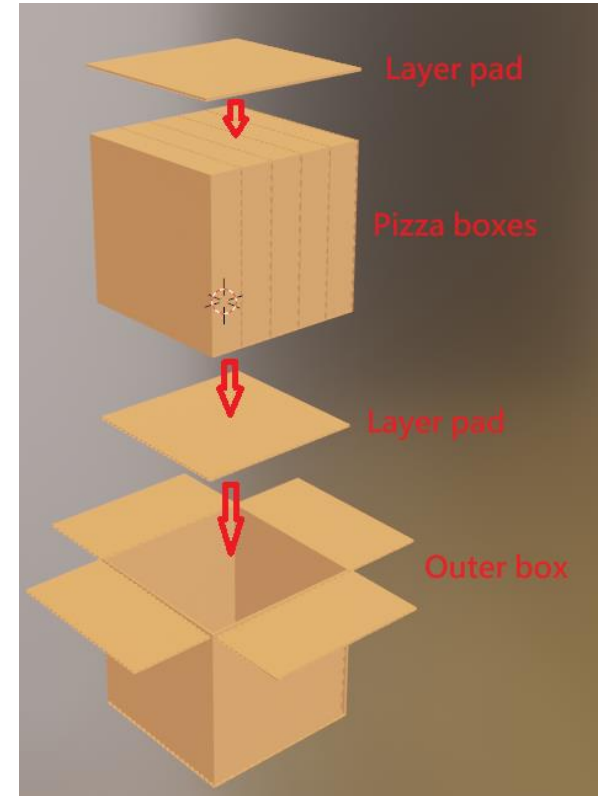


Figure 10. Pizza box, Layer pad & outer box packing way

## F1 Smart Module Packing Label location

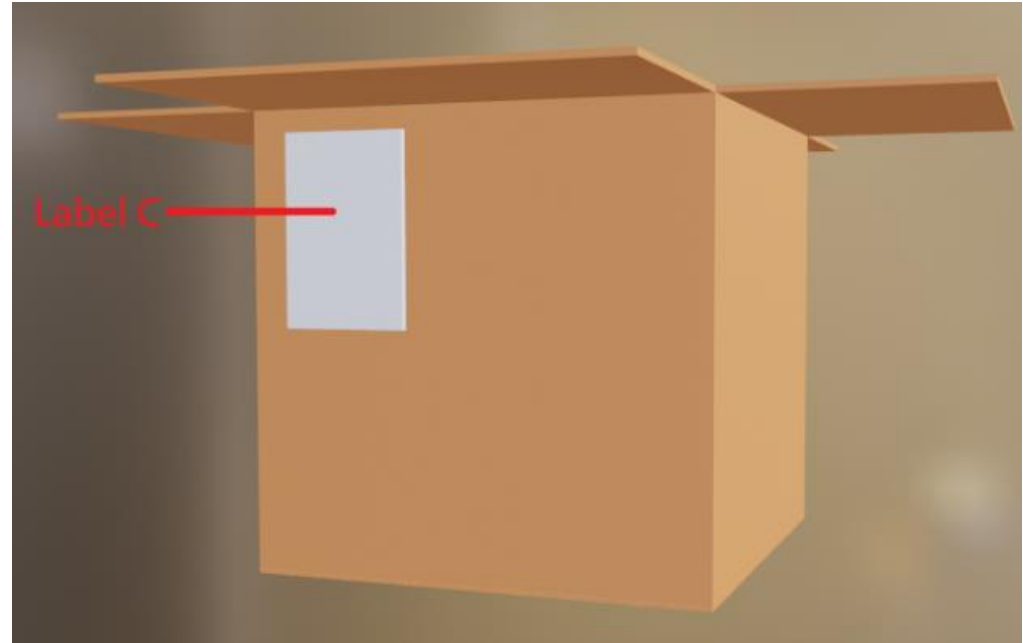
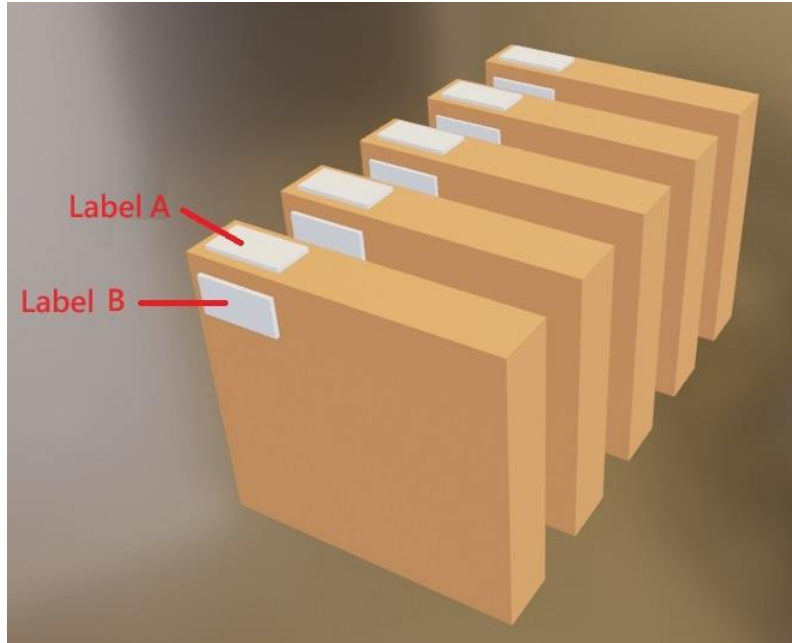


Figure 11. Pizza box & outer box label locations